

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S40	196	(flip near chip) near5 (wirebond\$3 or wire near bond\$3) and (flip near chip) near3 (underfill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 09:10
S39	3702	(flip near chip) near5 (wirebond\$3 or wire near bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/07 09:09
S38	225	438/122.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 17:16
S37	82	257/796.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 17:09
S36	397	257/712.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 15:56
S35	149	257/707.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 15:38
S34	339	257/706.ccor.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 15:12
S33	381	(substrate or package or packaging or circuit adj board or wiring near board or pcb or pwb or interposer) near3 (strip) and (heatsink or heat adj sink) near5 (ic or chip or die or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 14:15
S32	123	(substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) near6 (chip or die or ic or integrated adj circuit) near20 ((thermal\$2 or heat\$2) near2 (interface or adhesive) or tim)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 13:56
S31	307	(chip or die or integrated adj circuit or ic) and (substrate or leadframe or frame or package or packaging or housing) near2 (strip or tape) and (heatsink or (heat or thermal\$2) near2 (sink or spread\$3)) and (encapsulat\$4 or encapsulant or molding or mold) near6 (open or expos\$4 or uncover\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 13:22

EAST Search History

S30	525	(underfill\$4) near5 (cte or thermal near expan\$4 or solder near fatigue or solder near joint)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 13:20
S29	159	(flip near chip) near10 (underfill\$4) near10 (cte or thermal near expan\$4 or solder near fatigue or solder near joint)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 13:20
S26	109	("20020079570" "3908075" "3942245" "4501960" "4674175" "4701781" "4975765" "5023202" "5041395" "5122860" "5157475" "5172213" "5175612" "5285105" "5334857" "5366933" "5420460" "5474957" "5482736" "5482898" "5485037" "5556807" "5596231" "5596485" "5620928" "5650593" "5672548" "5672909" "5679978" "5693572" "5708567" "5729432" "5736785" "5789813" "5796163" "5807768" "5854511" "5867368" "5874321" "5886397" "5894108" "5900676" "5939784" "5940271" "5949655" "5950074" "5962810" "5981314" "5982621" "5986336" "5986340" "6011304" "6028354" "6034429" "6049125" "6069023" "6081028" "6081029" "6091603" "6092281" "6097101" "6104086" "6111324" "6117193" "6117705" "6127724" "6143588" "6150193" "6162849" "6163458" "6165612" "6191360" "6196002" "6198163" "6206997" "6208519" "6212070" "6214644" "6219238" "6222263" "6228676" "6229200" "6229702" "6236568" "6242281" "6246566" "6258629" "6265771" "6266197" "6274927" "6281241" "6281568" "6285075" "6291884" "6294100" "6294830" "6326678" "6395578" "6396143" "6429048" "6429508" "6433360" "6444498" "6452255" "6458626" "6498099" "6507102" "6552417" "6556740").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 13:16
S25	5	("20010019181" "5216278" "5610442" "6198171" "6246115").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 13:02

EAST Search History

S24	30	("20010015492" "20020005578" "20020006718" "20020180035" "20020185734" "20030034569" "5172213" "5311060" "5339216" "5444025" "5493153" "5610442" "5639694" "5650663" "5679978" "5705851" "5736785" "5773362" "5877552" "5977626" "5986885" "6037658" "6236568" "6251706" "6323066" "6414385" "6462405" "6525421" "6631078" "6656770"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/06 12:56
S23	12	"6933176".pn. "6734552".pn. "6309915".pn. "6853070".pn. "6559537".pn. "20020149092"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/06 12:52